

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Applicant : Kin P. Cheung
Serial No. : (Unknown)
Filed : October 22, 2003
For : PROCESSES FOR HERMETICALLY PACKAGING
WAFER LEVEL MICROSCOPIC STRUCTURES
Examiner : (Unknown)
Group Art Unit : (Unknown)
Atty Docket No. : 879.1.004

EXPRESS MAIL CERTIFICATE	
DATE	October 22, 2003
LABEL NO.	EV 026600038 US
I HEREBY CERTIFY THAT, ON THE DATE INDICATED ABOVE, I DEPOSITED THIS PAPER OR FEE WITH THE U.S. POSTAL SERVICE AND THAT IT WAS ADDRESSED FOR DELIVERY TO THE COMMISSIONER FOR PATENTS, ALEXANDRIA, VA 22313-1450 BY "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE.	
NAME (PRINT)	Albert Hsu
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October 22, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Transmitted herewith is an Information Disclosure Statement ("IDS") in the above-referenced Application, together with a Form-1449 listing all references cited and a copy of each reference.

This IDS is being mailed within three (3) months of filing of the above-captioned Application, if it is a National Application, or within three (3) months of entering, as set forth in 37 C.F.R. § 1.491, the national stage of the above-captioned Application, if the above-captioned Application is an International Application. Therefore, consideration of the IDS by 5 the Patent and Trademark Office, without the payment of any additional fee, is believed to be due under 37 C.F.R. § 1.97(b). However, the Commissioner is hereby authorized to charge Deposit Account No. 23-0510 if any fee under 37 C.F.R. 1.17 is deemed necessary for the accompanying references to be considered by the Patent and Trademark Office

10 All the references are in English and/or are cited in an accompanying English language version of the Search Report by another Patent Office, so that comment on the references by the Applicant is not required under 37 C.F.R. § 1.98(a).

Respectfully submitted,



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Sheet _____ of _____

Form PTO-1449 (REV. 8-83) INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)			ATTY. DOCKET NO. 879.1.004		SERIAL NO. Unknown			
			APPLICANT(S) Kin P. Cheung					
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			U.S. PATENT DOCUMENTS					
Examiner Initial		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES NO	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)								
		Y.T. Cheng et al.; Vacuum Packaging Technology Using Localized Aluminum/Silicon-to-Glass Bonding; Center for Wireless Integrated Microsystems; University of Michigan; IEEE 0-7803-5998-4/01; 2001 (pages 18-21).						
		C. Yu et al.; Antireflection Coatings for Advanced Semiconductor Device Metallization Using Laser Reflow and Chemical Mechanical Planarization; Appl. Phys. Lett. 59 (16), 10/14/91 (pages 1978-1980).						
		Ruichen Liu, K. P. Cheung, and W. Y.-C. Lai; A Study of Pulsed Laser Planarization of Aluminum for VLSI Metallization; AT&T Bell Laboratories; 1989 VMIC Conference 6/12-13/89; 1989 IEEE TH-0259-2/89/0000-0329 (pages 329-335).						
		B. Woratschek et al.; Improved Excimer Laser Planarization of AlSi with Addition of Ti or Cu; Siemens AG; 1989 VMIC Conference 6/12-13/89; 1989 IEEE TH-0259-2/89/0000-0309 (pages 309-314)						
Examiner				DATE CONSIDERED				
<p>* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>								